

Abstract

A method for using an excimer laser to pattern electrodeposited photoresist on a sloped surface of a wafer substrate includes depositing a layer of photoresist on top of a substrate that includes a sloped surface and scanning an excimer laser beam over the layer of photoresist to expose the layer of photoresist in a desired pattern. The scanning step includes projecting the excimer laser beam in a small beam spot onto the substrate and scanning the small beam spot of the excimer layer beam relative to the substrate to define the pattern sequentially onto the substrate, including the sloped surface.

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